

NSM2402AT V2.0

QS-EP00-010

# NSM2402AT Top-Inlet Analog Silicon Microphone Specification

Rev. 2.0



#### 1. GENERAL DESCRIPTION

NSM2402AT is a "slim-bodied" Silicon Microphone with analog output and top inlet for sound input. It is a cost-effective alternative to traditional electret condenser microphone (ECM). Provided on tap-and-reel, it is ideally suited for high volume applications. And it can be processed directly to customer's PCB using standard automatic pick-and-place equipment and surface mounted via standard solder reflow equipment.

NSM0402AT can be used in (but not limited to) the following applications:

- 1. Portable communication device
- 2. Notebook and desktop
- 3. Headphone and headset accessories

#### 2. ABSOLUTE MAXIMUM RATINGS

| Supply voltage: VDD to GND | 0.3V~5V |
|----------------------------|---------|
| ESD Tolerance              |         |
| The Lid Mode               | 8kV     |
| The I/O Pin Mode           | 4kV     |

| TEMPERATURE CHARACTERISTICS           |                    |     |  |      |    |
|---------------------------------------|--------------------|-----|--|------|----|
| Parameter Conditions Min Typ Max Unit |                    |     |  |      |    |
| Operating Temperature                 |                    | -40 |  | +85  | °C |
| Store on Tommeroture                  | Solder on PC board | -40 |  | +105 | °C |
| Storage Temperature                   | In Tape and Reel   | -10 |  | +50  | °C |

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#### **3. ACOUSTIC & ELECTRICAL SPECIFICATIONS**

Unless otherwise specified, test conditions are:

Typical specification are measured at  $V_{DD} = 3.0V$ 

Input sound pressure  $P_{IN} = 94$ dB SPL@1kHZ

Test room temperature Ta = 25 °C, Room Humidity =  $50 \pm 20\%$ 

SNR & noise floor measurement is based on 20 - 20 KHz pass band with A-Weighting

Filter applied

| PERFORMANCE  |                                |       |           |     |        |
|--|--------------------------------|-------|-----------|-----|--------|
| Parameter  | Conditions                     | Min   | Тур       | Max | Unit   |
| Directivity  |                                | Omni- | Direction | nal |        |
| Sensitivity  | @1KHz (0 dB = 1V/Pa)           | -45   | -42       | -39 | dB     |
| Signal-to-Noise Ratio  | @1KHz (0 dB = 1V/Pa)           |       | 58        |     | dB     |
| Total Harmonic Distortion<br>(THD) @ 100dB SPL   | @1KHz                          |       | 0.2       | 0.5 | %      |
| Total Harmonic Distortion<br>(THD) @ 115dB SPL   | @1KHz                          |       | 0.5       | 1   | %      |
| Max Input Sound Pressure   | @1KHz, THD < 10%               |       | 130       |     | dB SPL |
| Power Supply Rejection<br>(PSR)  | 217Hz,100m Vpp square wave     |       | -84       | -79 | dB     |
|  | INPUT CHARACTERISTIC           | CS    |           |     |        |
| Power supply Voltage   |                                | 1.6   |           | 3.6 | V      |
| SensitivityLossAcrossChangeinsensitivityfromPower Supply Voltage1.6V to3.6V power supplyNo changevoltage |                                |       |           | dB  |        |
| Total Operation Current  | 1.6V-3.6V power supply voltage |       | 160       | 200 | uA     |
| Standby Current  | 1.6V-3.6V power supply voltage |       |           | 2   | uA     |
| OUTPUT CHARACTERISTICS   |                                |       |           |     |        |
| Output Impedance   | @1KHz (0 dB = 1 V/Pa)          |       |           | 200 | Ω      |

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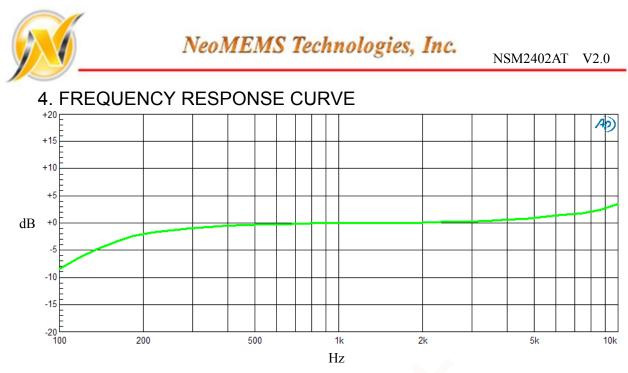
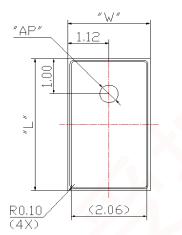
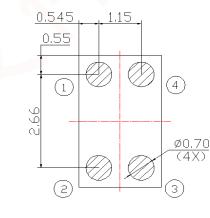


Figure 1. Typical free field frequency response (Normalized to 1 KHz)

<u>"H</u>"

#### 5. MECHANICAL SPECIFICATIONS





| ITEM      | DIMENSION | TOLERANCE  | UNITS |     | PIN OUTPUT |            |
|-----------|-----------|------------|-------|-----|------------|------------|
| LENGTH(L) | 3.76      | ±0.10      | mm    | PIN | ¥          | FUNCTION   |
| WIDTH(W)  | 2.24      | ±0.10      | mm    | 1   |            | POWER(Vdd) |
| HEIGHT(H) | 1.10      | $\pm 0.10$ | mm    | 2   |            | GROUND     |
| ACOUSTIC  |           |            |       | 3   |            | GROUND     |
| PORT(AP)  | Ф0.50     | $\pm 0.10$ | mm    | 4   |            | OUTPUT     |

(09)

m

R0.10

(4X)

Note:

Dimensions are in millimeters unless otherwise specified. Tolerance  $\pm 0.15$ mm unless otherwise specified

Figure 2. Detailed mechanical drawings

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#### 6. RECOMMENDED CUSTOMER LANDING PATTERN

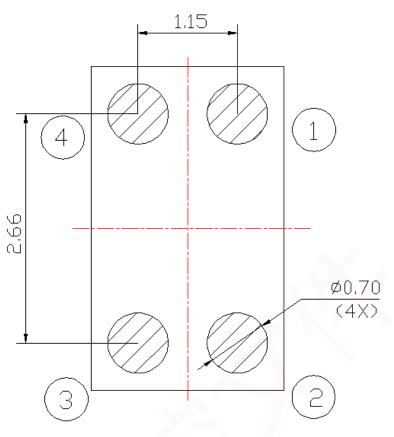


Figure 3. Recommended landing pattern on customers' PCB

#### 7. RECOMMENDED INTERFACE CIRCUIT

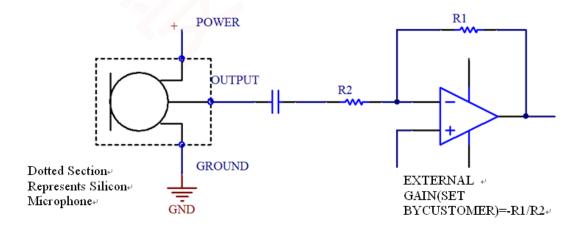
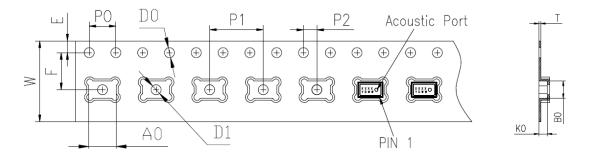


Figure 4. Recommended interface circuit for customers' applications

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#### 8. PACKAGING SPECIFICATIONS



| D0 | 1.5±0.1         | W  | 12.0±0.30       |
|----|-----------------|----|-----------------|
| D1 | $1.5 \pm 0.1$   | Е  | $1.75 \pm 0.10$ |
| A0 | $4.06 \pm 0.10$ | F  | $5.50 \pm 0.10$ |
| B0 | $2.54 \pm 0.10$ | PO | $4.00 \pm 0.10$ |
| K0 | $1.35 \pm 0.10$ | P1 | $8.0 \pm 0.10$  |
| Т  | 0.3±0.05        | P2 | 2.00±0.10       |

Notes:

(1) Tape & Reel Per EIA-481 standard;

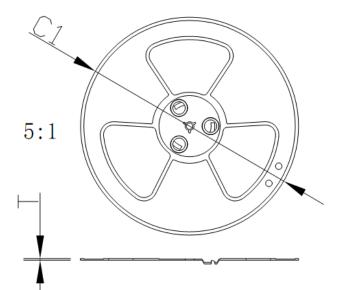
(2) Label applied to external package and direct to reel

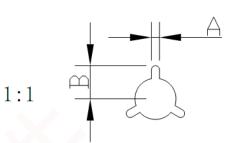
| Order Part Number | Reel Diameter | Qty per Reel |
|-------------------|---------------|--------------|
| NSM2402AT         | 13"           | 5,000        |

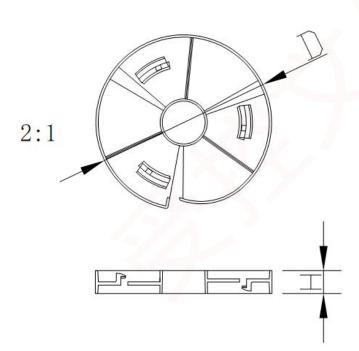
Figure 5. Tape Specification

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| SPEC         | 13"  |
|--------------|------|
| $C1 \pm 1.0$ | Ф330 |
| A±0.2        | 2.6  |
| B±0.2        | 10.8 |
| T±0.2        | 2.0  |

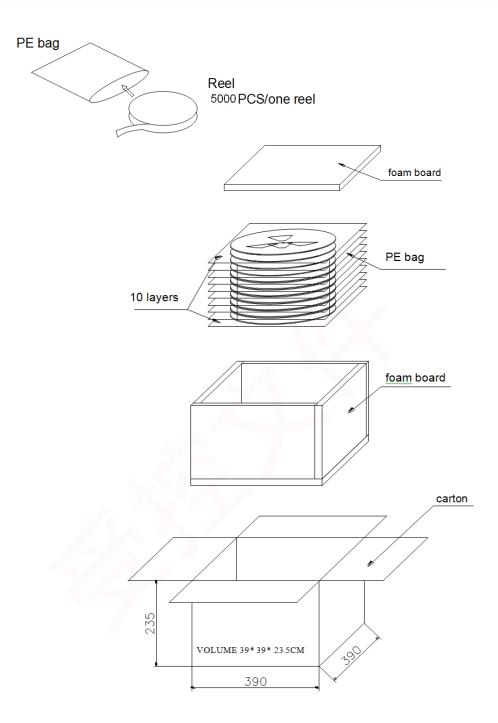
| Available Reel Size(mm)    |      |      |  |  |
|----------------------------|------|------|--|--|
| Tape Width $D \pm 0.5$ H+1 |      |      |  |  |
| 12                         | Φ100 | 12.5 |  |  |

#### 5,000PCS PRODUCTS/1 reel

Figure 6. Reel Specification

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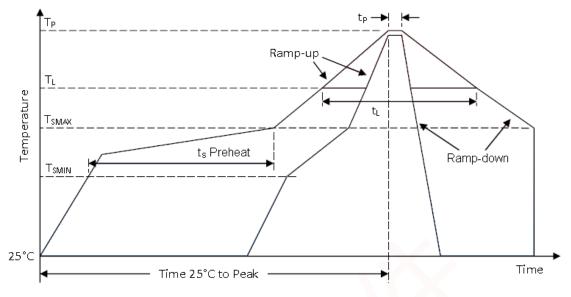
50,000 Pieces of Products per Carton

Figure 7. Packaging Specification

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#### 9. SOLDER REFLOW PROFILE



| Profile Feature  | Pb-Free                          |  |
|--|----------------------------------|--|
| Average Ramp-up rate (T <sub>SMAX</sub> to T <sub>P</sub> )  | 3°C/second max.                  |  |
| Preheat<br>Temperature Min $(T_{SMIN})$<br>Temperature Max $(T_{SMAX})$<br>Time $(T_{SMIN}$ to $T_{SMAX})$ $(t_S)$ | 150°C<br>200°C<br>60-180 seconds |  |
| Time maintained above:<br>Temperature (T <sub>L</sub> )<br>Time (t <sub>L</sub> )                                  | 217℃<br>60-150 seconds           |  |
| Peak Temperature (T <sub>P</sub> )   | 260°C                            |  |
| Time within 5°C of actual Peak Temperature ( $t_P$ )   | 20-40 seconds                    |  |
| Ramp-down rate( $T_P$ to $T_{SMAX}$ )  | 6°C/second max                   |  |
| Time 25°C to Peak Temperature  | 8 minutes max                    |  |

Figure 8. Recommended leadless solder reflow temperature profile

Notes:

- 1. Vacuuming over acoustical hole of the microphone is not allowed, because the Devices can be damaged by vacuum.
- 2. Washing the board after reflow process is not allowed, because board washing and Cleaning agents can damage the device. A device should not be exposed to ultrasonic processing or cleaning.
- 3. Recommended number of reflow is no more than 5 Times.

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### **10. RELIABILITY SPECIFICATIONS**

| Test item                 | Detail  | standard                  |
|---------------------------|---|---------------------------|
| Reflow Simulation         | Refer to Sec.9 for solder reflow profile, total 5 times   | /                         |
| Low Temperature Bias      | Conditions:-40°C<br>Duration:168 hours while under<br>bias  | IEC 60068-2-2<br>Test Aa  |
| High Temperature Bias     | Conditions: 105°C<br>Duration:168 hours while under<br>bias   | IEC 60068-2-2<br>Test Ba  |
| Thermal Shock             | Conditions:<br>100 cycles of air-air thermal<br>shock from -40 °C to 125 °C<br>with 15-minute soaks                                   | IEC 60068-2-4             |
| Temperature/Humidity Bias | Conditions:<br>85°C/85%RH environment while<br>under bias for 168 hours   | JESD 22-A101A-B           |
| Mechanical Shock          | Conditions:3 pulses of 10,000g in the X,Y and Z direction   | IEC 60068-2-27<br>Test Ea |
| Vibration Test            | Test axis: X, Y, Z<br>Conditions : 2~400Hz 1 oct/min<br>Test time : 15 mins per axis<br>Use fixture during the testing                | IEC 60068-2-6             |
| Drop Test                 | Conditions: For each sample,<br>drop by all corners, edges,<br>surfaces respectively. Steel floor.<br>Drop height: 1800mm.            | IEC 60068-2-32            |
| ESD                       | Conditions:<br>$\pm$ 8KV direct contact to the lid<br>when unit is grounded , $\pm$ 4KV<br>direct contact to the I/O pins.10<br>times | IEC 61000-4-2             |

Note: Immediately after reliability test, the samples shall be stored under climatic conditions such as that normally exist in ordinary rooms or laboratories. Unless otherwise noted, the recovery period shall be 2 hours at least before performance testing after test condition is performed, the sensitivity of the microphone shall not deviate more than 3dB from its initial value.

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#### 11. REVISION HISTORY:

| Version | Date       | Description   | Change from                     | Change to                        |
|---------|------------|---|---------------------------------|----------------------------------|
| 1.0     | 08/09/2011 | Initial release   |                                 |                                  |
| 1.1     | 06/06/2012 | Updated the dimension of cap  |                                 |                                  |
| 1.2     | 14/06/2012 | Update mechanical specification and<br>Solder reflow profile  |                                 |                                  |
| 1.3     | 02/07/2012 | Updated Reel specification  |                                 |                                  |
| 1.4     | 20/08/2012 | Updated Vibration Test  |                                 |                                  |
| 1.5     | 10/10/2012 | Updated absolute maximum ratings  |                                 |                                  |
| 1.6     | 27/02/2013 | <ol> <li>Section4 unit dBFS change to dB</li> <li>Update metal cap dimension</li> <li>Delete the dimension not related to<br/>the specifications marked in packaging</li> <li>Updated Mechanical Shock</li> <li>Updated Drop Test.</li> </ol> | 2.12mm×3.66mm<br>JEC 60068-2-27 | 2.06 mm×3.60mm<br>IEC 60068-2-27 |
| 1.7     | 10/05/2013 | Updated solder reflow profile   |                                 |                                  |
| 1.8     | 03/06/2013 | Updated section 7   |                                 |                                  |
| 1.9     | 19/07/2013 | Updated section 8 packaging specification   |                                 |                                  |
| 2.0     | 17/01/2014 | Updated test voltage  |                                 |                                  |
|         |            |   |                                 |                                  |
|         |            |   |                                 |                                  |
|         |            |   |                                 |                                  |
|         |            | 7   |                                 |                                  |
|         |            |   |                                 |                                  |

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